ABSTRACT OF THE DISCLOSURE

METHOD FOR MANUFACTURING SEMICONDUCTOR CHIPS

In a process of manufacturing semiconductor chips (C), first, the reverse of a wafer (W), on the obverse of which many chips (C) are formed, is ground so as to shape the wafer (W) with a predetermined thickness. Then, the reverse of the wafer (W) is polished or etched so that the broken layer which is formed during the back grinding is removed. Next, grooves (G) are formed on the obverse of the wafer (W) in a predetermined depth along streets (S) formed between the chips (C). Finally, the wafer (W) is cleft along the grooves (G) so as to be divided into separate chips (C). By this process, the broken layer formed on the reverse of the wafer (W) is removed after the back grinding, then the wafer (W) is divided into separate chips (C) by use of the cleavage; therefore, chipping is effectively reduced.

(Fig. 1)